

SURFACE MOUNT RECTIFIER

VOLTAGE RANGE: 50 --- 1000 V
CURRENT: 1.0 A

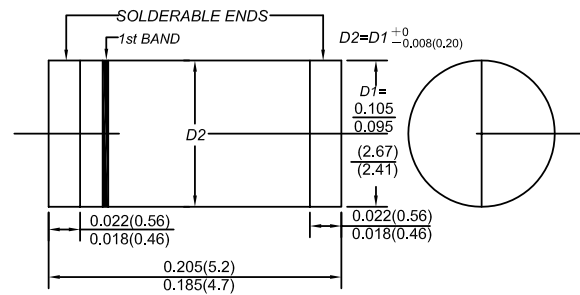
FEATURES

Plastic package has underwriters laboratories
flammability classification 94V-0
Glass passivated chip junction
For surface mount applications
High temperature metallurgically bonded construction
Cavity-free glass passivated junction
High temperature soldering guaranteed:450 /5 seconds
at terminals.Complete device sub-mersible temperature
of 265 for 10 seconds in solder bath

MECHANICAL DATA

Case: JEDEC DO-213AB,molded plastic
Terminals: Plated terminals,solderable per
MIL- STD-750,Method 2026
Polarity: Color band denotes cathode
Weight: 0.0046 ounces, 0.116 grams
Mounting position: Any

DO - 213AB



MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25 ambient temperature unless otherwise specified.

Single phase, half wave, 60 Hz, resistive or inductive load. For capacitive load, derate current by 20%.

		GL 41A	GL 41B	GL 41D	GL 41G	GL 41J	GL 41K	GL 41M	UNITS
Maximum recurrent peak reverse voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	V_{DC}	50	100	200	400	600	800	1000	V
Maximum average forward rectified current (see FIG.1)	$I_{(AV)}$	1.0							A
Peak forward surge current 8.3ms single half-sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	30							A
Maximum instantaneous forward voltage @1.0A	V_F	1.1					1.2		V
Maximum reverse current @ $T_A=25$ at rated DC blocking voltage @ $T_A=125$	I_R	10					50		μA
Typical junction capacitance (Note1)	C_j	8.0							pF
Typical thermal resistance (Note 2)	$R_{\theta JA}$	75							/W
Operating junction temperature range	T_j	- 55 ---- +175							
Storage temperature range	T_{STG}	- 55 ---- +175							

NOTE: 1. Measured at 1.0MHz and applied reverse voltage of 4.0V DC.

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2. Thermal resistance from junction to ambient, 0.24x0.24"(6.0x6.0mm) copper pads to each terminal.

FIG.1 – FORWARD DERATING CURVE

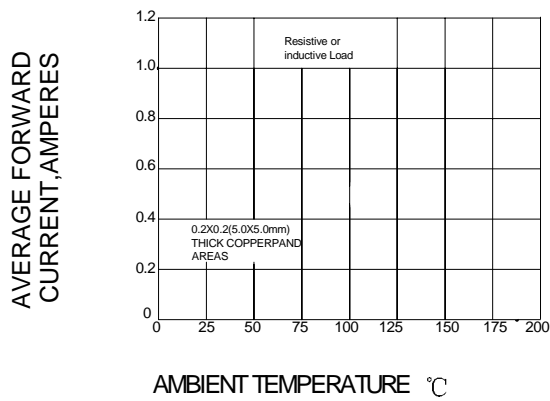


FIG.2 PEAK FORWARD SURGE CURRENT

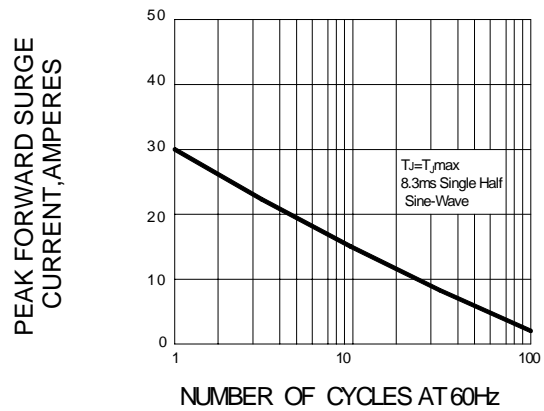


FIG.3 – TYPICAL FORWARD CHARACTERISTICS

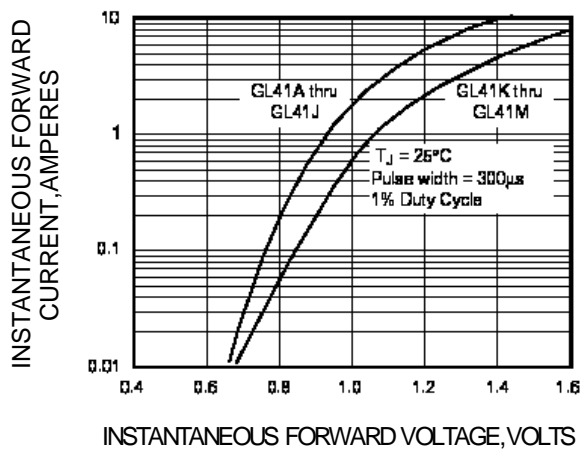


FIG.4 – TYPICAL REVERSE CHARACTERISTICS

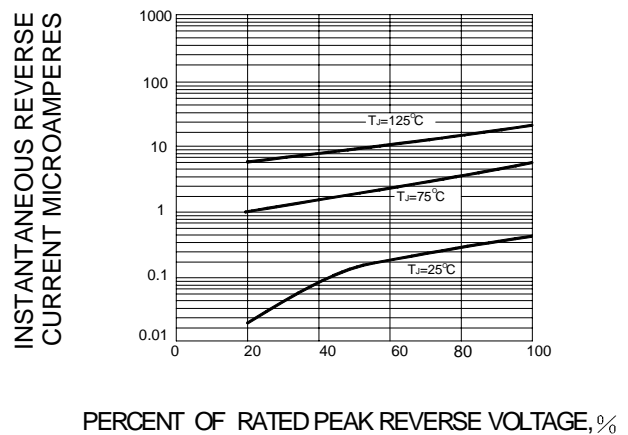


FIG.5-TYPICAL JUNCTION CAPACITANCE

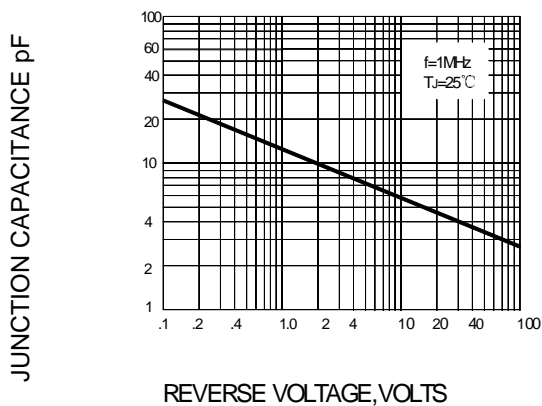


FIG.6-TRANSIENT THERMAL IMPEDANCE

